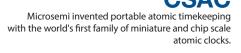


Chip-Scale Atomic Clock



Choose CSAC for best-in-class stability, size, weight, and power consumption.



Features

- Power consumption <120 mW
- Less than 17 cc volume, 1.6" x 1.39" x 0.45"
- Radiation-tolerant: 20 krad
- SEL, SEU tested to 64 MeV-cm²/mg (contact factory for details)
- 10 MHz CMOS-compatible output
- 1PPS output and 1PPS input for synchronization
- RS-232 interface for monitoring and control
- Short-term stability (Allan Deviation) of 3.0×10^{-10} at TAU = 1 sec

Applications

- Satellite timing and frequency control
- Satellite clock reference
- Assured position, navigation, and timing (PNT)
- Atomic clock accuracy
- Satellite cross-linking

The Microsemi SA.45s Commercial Space Chip-Scale Atomic Clock's (CSAC) potential for low size, weight, and power (SWaP), and high timing performance at relatively low cost makes it very attractive for low Earth orbit (LEO) applications. In addition to being a stand-alone atomic clock with a 10 MHz output, the CSAC also has a 1PPS output and can be disciplined with a 1PPS input. The Space CSAC retains this functionality and is a timing module that can be disciplined with a GPS-derived 1PPS input.

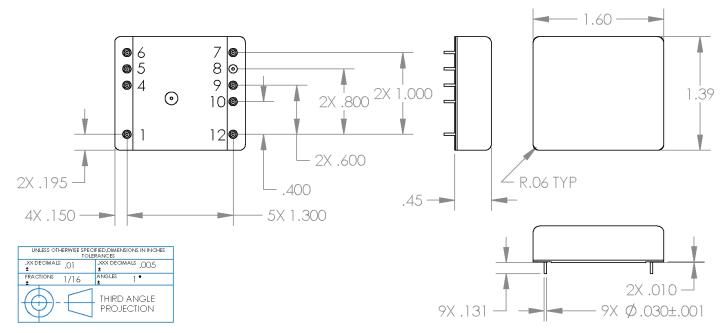
The SA.45s provides 10 MHz and 1PPS outputs at standard CMOS levels, with short-term stability (Allan Deviation) of 3.0×10^{-10} at TAU = 1 sec, typical long-term aging of $<9 \times 10^{-10}$ /month, and maximum frequency change of $\pm 5 \times 10^{-10}$ over an operating temperature range of -10 °C to 70 °C.

A standard CMOS-level RS-232 serial interface is built into the SA.45s. This is used to control and calibrate the unit and to provide a comprehensive set of status monitors. The interface is also used to set and read the CSAC's internal time-of-day clock.



Chip-Scale Atomic Clock

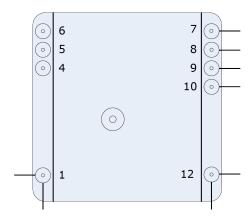
Mechanical Interface



Pin Description

Pin Number	ID	
1	Tune	
2	N/A	
3	N/A	
4	BITE	
5	Tx	
6	Rx	
7	Vcc	
8	GND	
9	1 PPS IN	
10	1 PPS OUT	
11	N/A	
12	10 MHz OUT	

Bottom View





Chip-Scale Atomic Clock

Specifications1

Electrical

RF Output

 Frequency 10 MHz Format **CMOS** Amplitude 0 V to Vcc Load impedance 1 MO Quantity

1PPS Output

 Rise/fall time <10 ns (10%-90%) at load capacitance 10 pF

 Pulse width 100 µs Level 0 V to Vcc • Logic high (VoH) min 2.80 V Logic low (Vol) max 0.30 V Load impedance 1 ΜΩ Quantity 1

1PPS Input

 Format Rising edge Low level < 0.5 V 2.5 V to Vcc High level • Input impedance 1 ΜΩ Quantity

Serial Communications

 Protocol RS232

CMOS 0 V to Vcc Format

 Tx/Rx impedance 1 ΜΩ Baud rate 57600

Built-In Test Equipment (BITE) Output

 Format CMOS 0 V to Vcc

 Load impedance 1 ΜΩ

 Logic 0= Normal operation

1= Alarm

Power Input

 Operating <120 mW <140 mW Warmup • Input voltage (Vcc) $3.3 \pm 0.1 \, \text{Vpc}$

Environmental

 Operating temperature -10 °C to 70 °C $\pm 5 \times 10^{-10}$

 Maximum frequency change over operating temp range (maximum rate of change 0.5 °C

per minute)

 Magnetic sensitivity $\pm 9 \times 10^{-11}$ /Gauss (≤2.0 Gauss)

 Radiated emissions Compliant to FCC part 15,

Class B, when mounted properly

onto host PCB

 Vibration Maintains lock under

MIL-STD-810, Method 514.5,

Procedure 1, 7.7 grms

0%-95% RH per MIL-STD-810. Humidity

Method 507.4

Storage and Transport (Non-operating)

 Temperature -55 °C to 85 °C

 Vibration MIL-STD-810, Method 514.5,

Procedure 1, 7.7 grms

• Shock (1 ms half-sine) 1000 g

Performance Parameters

 Warm-up time <180 s

 Analog tuning Range: $\pm 2.2 \times 10^{-8}$

Resolution: 1×10^{-11}

Input: 0 V-2.5 V into 100 k Ω

Range: $\pm 1 \times 10^{-6}$ Digital tuning

Resolution: 1×10^{-12}

Phase Noise (SSB)

Frequency	Frequency CSAC	
1 Hz	<-50 dBc/Hz	
10 Hz	<-70 dBc/Hz	
100 Hz	<-113 dBc/Hz	
1 kHz	<-128 dBc/Hz	
10 kHz	<-135 dBc/Hz	
100 kHz	<-140 dBc/Hz	

Frequency Accuracy

 Maximum offset at $\pm 5 \times 10^{-11}$ shipment

Maximum retrace

 $\pm 5 \times 10^{-10}$

(48 hrs off)

• 1 PPS sync ±100 ns



Chip-Scale Atomic Clock

Aging

Type ²	SA.45s ³
Monthly	<9 × 10 ⁻¹⁰
Yearly	<1 × 10 ⁻⁸

²After 30 days of continuous operation.

³All CSAC units are tested for aging specs as per the datasheet and meet the specs at the time of shipment. However, continuous operation of CSAC over extended period of time may yield unpredictable aging performance, resulting in failure to meet the aging specs and may not be suitable for certain applications.

Short-Term Stability (Allan Deviation)

Туре	SA.45s
τ = 1 s	3×10^{-10}
τ = 10 s	1 × 10 ⁻¹⁰
$\tau = 100 \text{ s}$	3 × 10 ⁻¹¹
τ = 1000 s	1 × 10 ⁻¹¹

Radiation Tolerance

Туре	SA.45s
TID	20 krad, $<5 \times 10^{-10}$ frequency offset change
SEL, SEU	Tested to 64 MeV-cm ² /mg (contact factory for details)

Physical

Solder

Hand solder using 63/37 tin/lead solder with maximum soldering tip of 329 $^{\circ}\text{C}$ (625 $^{\circ}\text{F}).$

Ordering Information

Part Number	Description	Output Frequency
090-02984-007	Space chip-scale atomic clock	10 MHz



Microsemi Headquarters

www.microsemi.com

One Enterprise, Aliso Viejo, CA 92656 USA Within the USA: +1 (800) 713-4113 Outside the USA: +1 (949) 380-6100 Sales: +1 (949) 380-6136 Fax: +1 (949) 215-4996 email: sales.support@microsemi.com

Microsemi, a wholly owned subsidiary of Microchip Technology Inc. (Nasdaq: MCHP), offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions, security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Learn more at www.microsemi.com.

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the Buyer's responsibility to independently determine suitability of any products and to test and verify the same. The information provided by Microsemi hereunder is provided "as is, where is" and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information itself or anything described by such information provided in this document is proprietary to Microsemi, and Microsemi reserves the right to make any changes to the information in this document or to any products and services at any time without notice.

©2018 Microsemi, a wholly owned subsidiary of Microchip Technology Inc. All rights reserved. Microsemi and the Microsemi logo are registered trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Microsemi: 090-02984-007